

## General Description

The 50N06 combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON).

This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

## Features

- 55A,60V.RDS(ON)=0.011Ω@VGS=10V
- N-channel-Enhancement mode
- Low Threshold Drive
- 100% Avalanche Tested
- Green Device Available

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current <sup>1</sup>	55	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current <sup>1</sup>	38	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	165	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	94	mJ
$I_{AS}$	Avalanche Current	38	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation	80	W
$T_{STG}$	Storage Temperature Range	-55 to 175	°C
$T_J$	Operating Junction Temperature Range	-55 to 175	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	2.1	°C/W

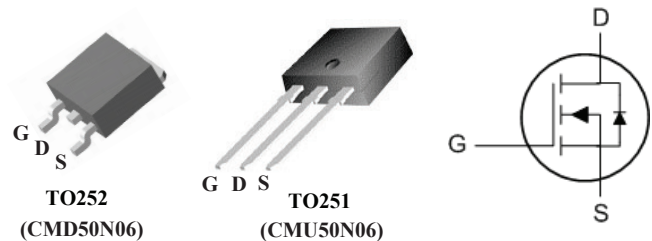
## Product Summary

BVDSS	RDSON	ID
60V	11mΩ	55A

## Applications

- DC-DC & DC-AC Converters
- Motor Control, Audio Amplifiers
- High Current, High Speed Switching
- Primary Switch for 12V and 24V system

## TO252 / TO251 Pin Configuration



TO252  
(CMD50N06)

TO251  
(CMU50N06)

## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25 °C, I <sub>D</sub> =250μA	---	0.065	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =55A	---	10.2	11	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2	---	4	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	μA
		V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	---	35	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.2	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =55A	---	42	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	11	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	8	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, V <sub>G</sub> =10V, R <sub>G</sub> =9.6Ω I <sub>D</sub> =55A	---	10.5	---	ns
T <sub>r</sub>	Rise Time		---	83	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	36	---	
T <sub>f</sub>	Fall Time		---	32	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	6200	7200	---	pF
C <sub>oss</sub>	Output Capacitance		---	850	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	690	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	55	A
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>		---	---	165	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =55A, T <sub>J</sub> =25°C	---	---	1.25	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=36A